

<b>PATENT ASSIGNMENT COVER SHEET</b>
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Electronic Version v1.1  
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EPAS ID: PAT4338345

<b>SUBMISSION TYPE:</b>	CORRECTIVE ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	Corrective Assignment to correct the SPELLING OF 3RD INVENTOR'S NAME previously recorded on Reel 026984 Frame 0714. Assignor(s) hereby confirms the ASSIGNMENT OF ASSIGNOR'S INTEREST.
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
TSUNG-DING WANG	03/23/2017
HUNG-JEN LIN	03/23/2017
CHIEN-HSUN LEE	03/23/2017
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	Taiwan Semiconductor Manufacturing Company, Ltd.
<b>Street Address:</b>	8, Li-Hsin Rd. 6, Hsinchu Science Park
<b>City:</b>	HsinChu
<b>State/Country:</b>	TAIWAN
<b>Postal Code:</b>	300-78
<b>PROPERTY NUMBERS Total: 2</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	13247529
<b>Application Number:</b>	14630265
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(972)732-9218
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	972-732-1001
<b>Email:</b>	docketing@slatermatsil.com
<b>Correspondent Name:</b>	SLATER MATSIL, LLP
<b>Address Line 1:</b>	17950 PRESTON RD., SUITE 1000
<b>Address Line 4:</b>	DALLAS, TEXAS 75252
<b>ATTORNEY DOCKET NUMBER:</b>	TSM11-0509
<b>NAME OF SUBMITTER:</b>	MARANDA BRALLEY
<b>SIGNATURE:</b>	/Maranda Bralley/
<b>DATE SIGNED:</b>	03/27/2017
<b>Total Attachments: 3</b>	
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**PATENT ASSIGNMENT**

Electronic Version v1.1  
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
Name	Execution Date
Tsung-Ding Wang	09/09/2011
Hung-Jen Lin	09/13/2011
Chien-Hsiun Lee	09/13/2011
<b>RECEIVING PARTY DATA</b>	
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.
Street Address:	No. 8, Li-Hsin Rd. 6
Internal Address:	Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77 R.O.C.
<b>PROPERTY NUMBERS Total: 1</b>	
Property Type	Number
Application Number:	13247529
<b>CORRESPONDENCE DATA</b>	
Fax Number:	(972)732-9218
Phone:	972-732-1001
Email:	docketing@slater-matsil.com
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>	
Correspondent Name:	Slater & Matsil, L.L.P.
Address Line 1:	17950 Preston Road
Address Line 2:	Suite 1000
Address Line 4:	Dallas, TEXAS 75252
ATTORNEY DOCKET NUMBER:	TSM11-0509
NAME OF SUBMITTER:	Kasey Edwards
Total Attachments: 1 source=TSM11-0509_Assignment#page1.tif	

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**PATENT**  
 REEL: 026984 FRAME: 0714  
**PATENT**  
 REEL: 042154 FRAME: 0486

ATTORNEY DOCKET NO.  
TSM11-0509

**ASSIGNMENT**

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and

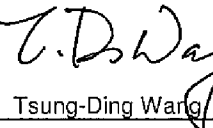
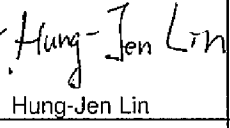
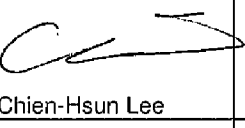
WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. ("Assignee"), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at 8, Li-Hsin Rd. 6 Hsinchu Science Park, Hsinchu 300-78 Taiwan, R.O.C., is desirous of acquiring my entire right, title and interest in and to said invention, and to said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to said Assignee, its successors and assigns, my entire right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all future non-provisional applications including divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to said Assignee, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to Assignee, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said Assignee, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said Assignee, its legal representatives, successors, or assigns, will testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said Assignee, its legal representatives, successors, and assigns, to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	Formation of Connectors without UBM			
SIGNATURE OF INVENTOR AND NAME	 Tsung-Ding Wang	 Hung-Jen Lin	 Chien-Hsun Lee	
DATE	3/23/17	3/23/17	3/23/17	
RESIDENCE	Tainan, Taiwan	Tainan, Taiwan	Chu-tung Town, Taiwan	